



# Techday

Taiwan | 2023

OUR TECHNOLOGY STARTS WITH YOU

**Sub-track II –  
Power & Energy Presentation**





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# 3 kW 5G telecom rectifier with SiC MOSFET and STM32G4 digital controller

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Power & Energy  
Competence  
Center



# Agenda

1 Background

4 ST products introduction

2 Introduction for 3 kW digital solution

5 Summary

3 EVM board performance

# Background

# 5G telecom power requirements

Higher system integration is the Key for 5G power  
Provides higher power density and higher efficiency!

- **Smaller coverage due to higher frequency radio:** to achieve high network speed and low latency
- **Higher power consumption in 5G usage:** to fulfill high traffic density and connection density

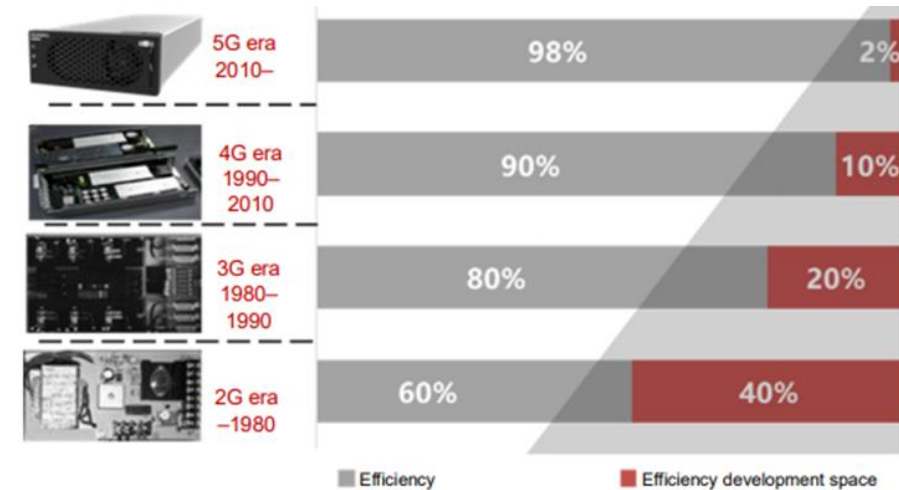
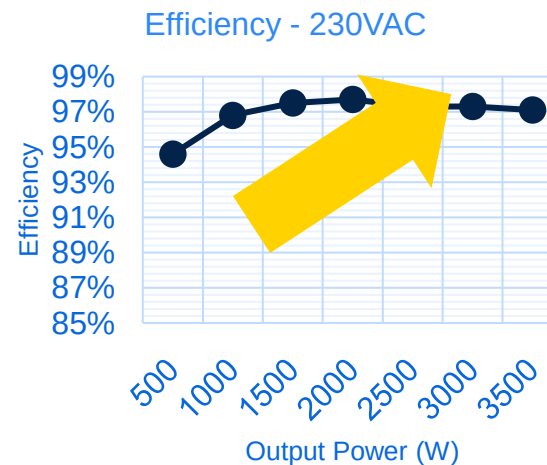
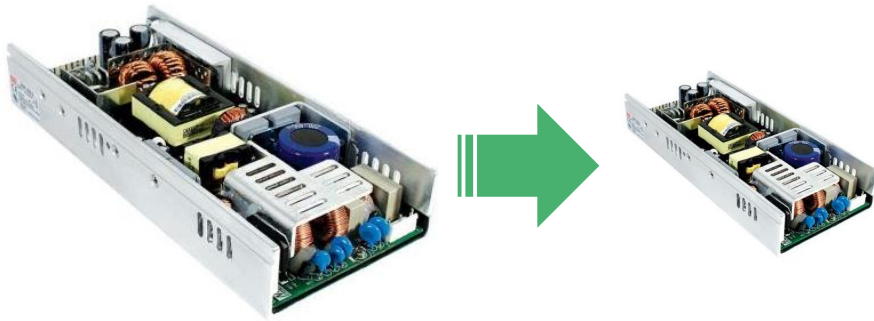


Source: Huawei

# Digital solution for 5G power applications

To achieve high system integration, we need:

- High flexibility and good adaptability for advanced topologies to achieve high efficiency
- Provide benefit on downsizing and BOM reduction
- Support communication for real-time monitoring (safety)
- Less component variation (high reliability)



Source: Huawei

# **Introduction for 3 kW digital solution**





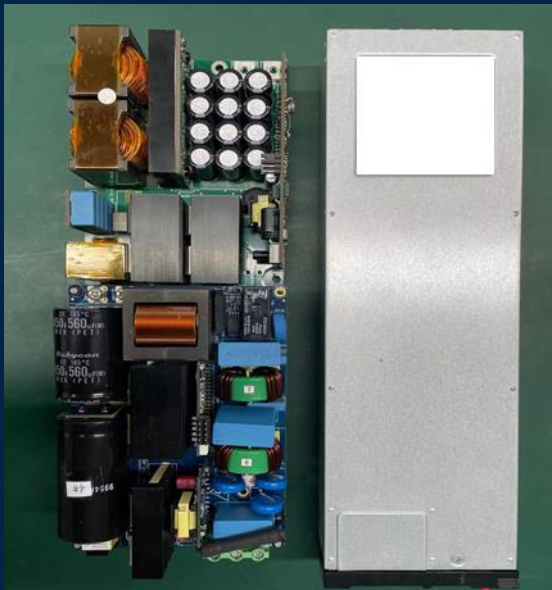
# Telecom rectifier/datacenter/server



## 3 kW CCM TTP PFC + FB LLC + SR–telecom rectifier

PE.SP\_0001.20

### Physical Sample



ST  
3 kW telecom  
Rectifier

Commercial  
2.9 kW  
telecom  
Rectifier

### Application key features:

- Fully digital AC-DC power supply
- Input AC voltage: 90–264 VAC
- Input AC frequency: 47–63 Hz
- DC output voltage: 53.5 VDC
- Peak efficiency > 96.5% @ 230 VAC
- Power Factor > 0.99 @ 100% load
- iTHD < 5% @ 100% load
- Hold up time: 10 ms
- Outline dimension: 100 x 310 x 41 mm
- Power density up to 40 W/inch<sup>3</sup>
- Peak inrush current < 30 A

### Key products

#### PFC:

- SCTW35N65G2V (SiC MOSFET),
- STY139N65M5 (SJ MOSFET),
- STGAP2D (galvanic insulated gate driver)
- STM32G4 (32-bit MCU)
- VIPER26HD (for aux. power of PFC stage)

#### LLC:

- STW70N65DM6 (SJ MOSFET),
- STGAP2HS (galvanic insulated gate driver)
- STL130N8F7 (SR MOSFET)
- STM32G4 (32-bit MCU)
- VIPER38HD (for aux. power of LLC stage)

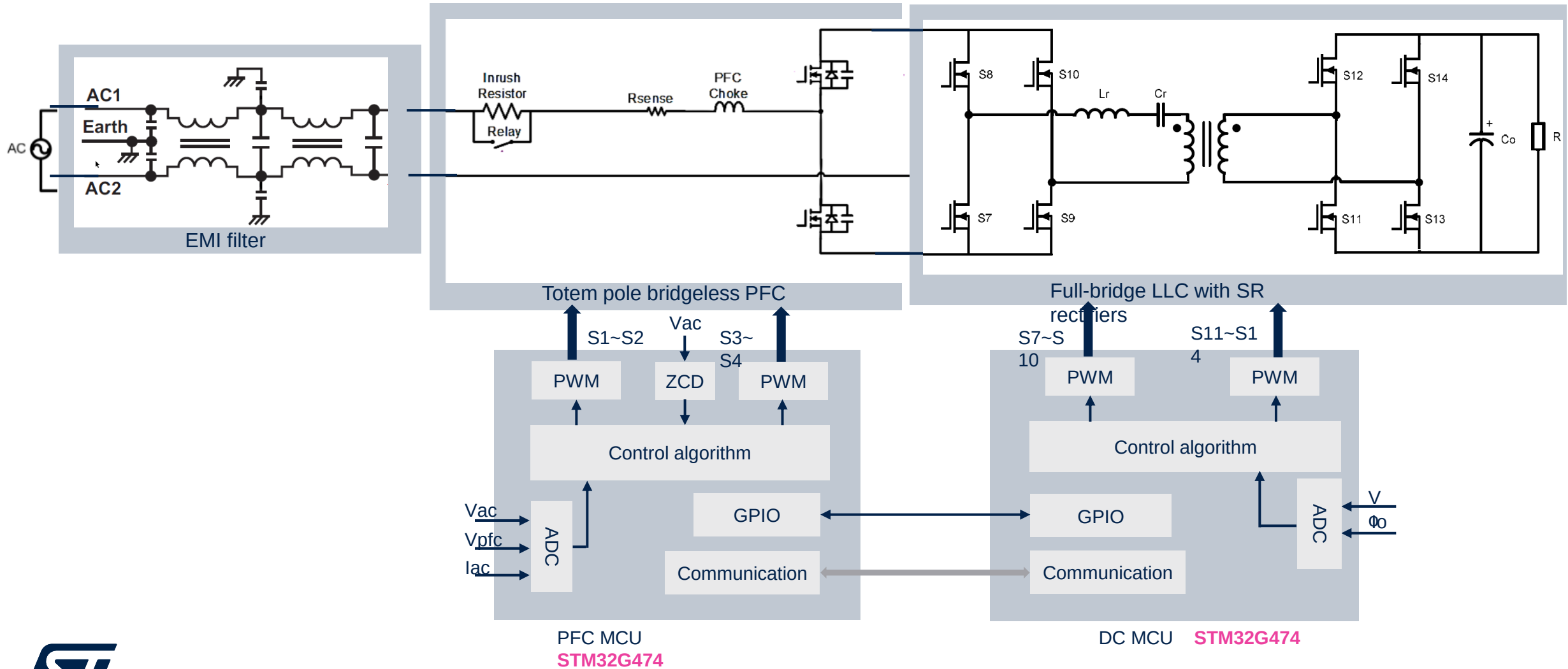
### Key benefits

- Peak efficiency > 96.5%
- Power density up to 40W/inch<sup>3</sup>





# Simplified block diagram

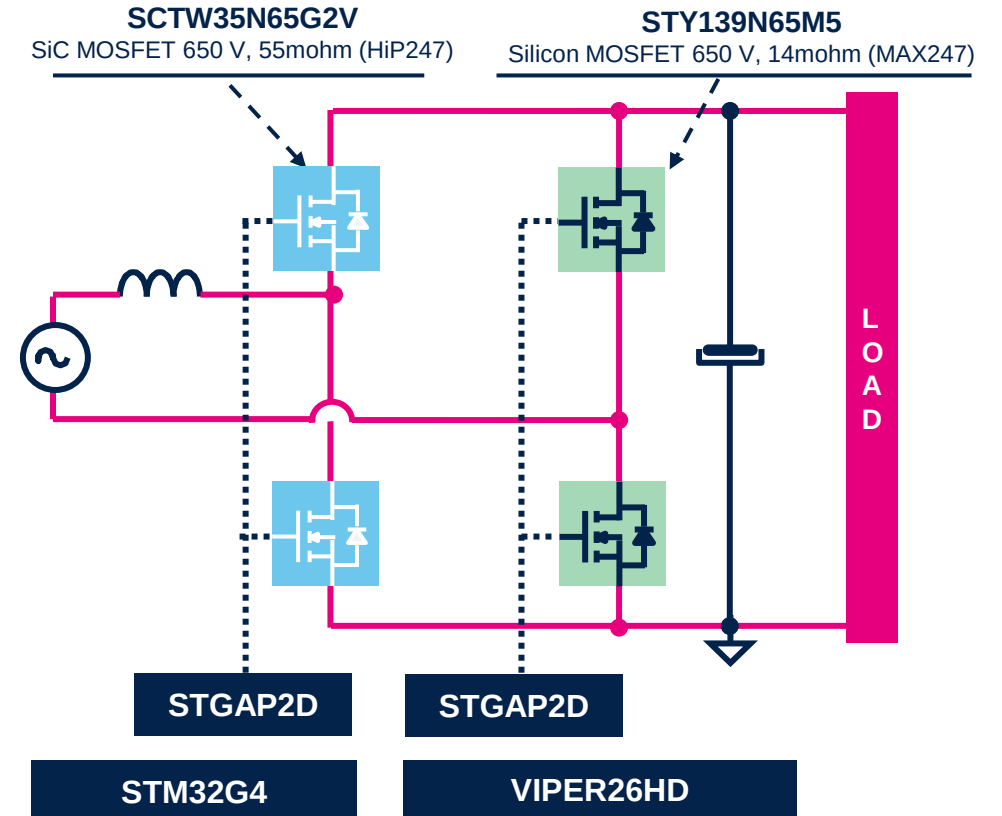




# 3 kW CCM totem pole PFC solution

## Key specs

- Input AC voltage: 90–264 VAC
- Input inrush current: <30 A
- Switching frequency: 70 kHz
- Operation mode: CCM
- Peak efficiency: 98.5% @ 230 VAC
- Power Factor > 0.99 @ 100% load
- iTHD < 5% @ 100% load
- STM32G4 digital power control



## Key products:

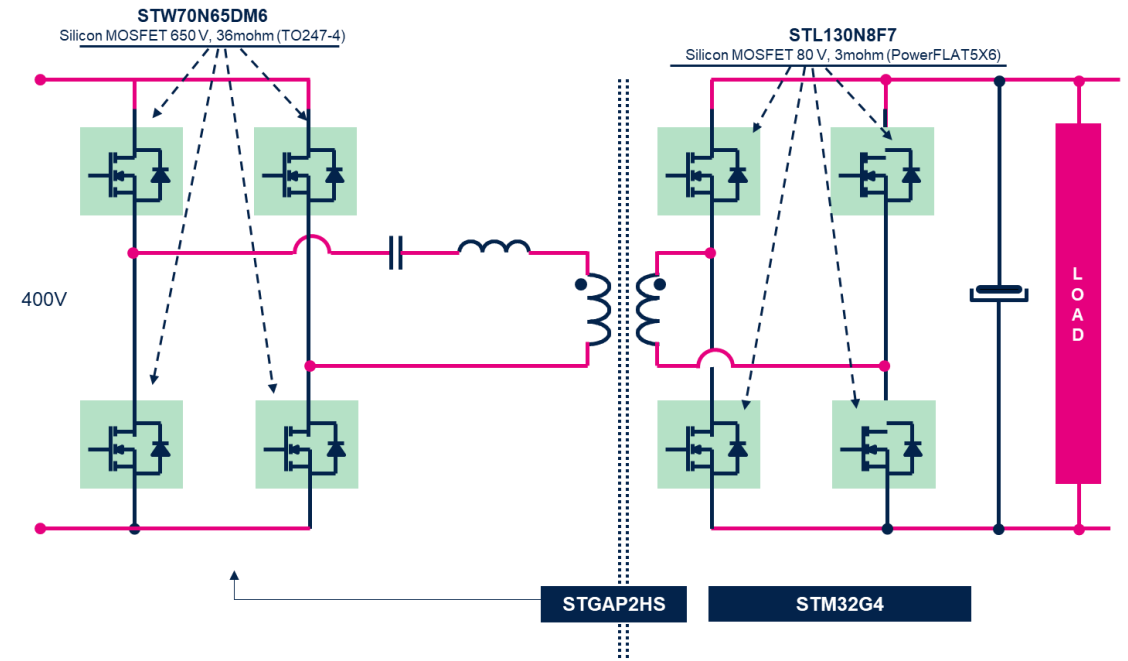
- SCTW35N65G2V (SiC MOSFET)
- STY139N65M5 (SJ MOSFET)
- STGAP2D (galvanic insulated gate driver)
- STM32G4 (32-bit MCU)



# 3 kW full-bridge LLC solution

## Key specs

- Input DC voltage: 350–425 V
- Output voltage: 53.5 V
- Switching frequency: 80 kHz–150 kHz
- Resonant frequency: 115 kHz
- Peak efficiency: 98.2%
- Output voltage dynamic response: < 5%
- Digital (STM32G4) power control



## Key products:

- STW70N65DM6 (HV MOSFET)
- STL130N8F7 (SR MOSFET)
- STGAP2HS (galvanic insulated gate driver)
- STM32G4 (32-bit MCU)
- VIPER38LD (converter for aux. PS)

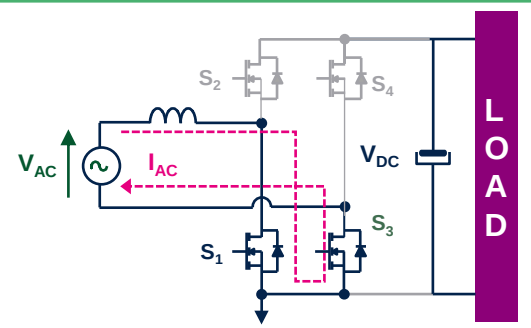


# Operation mode of totem pole PFC

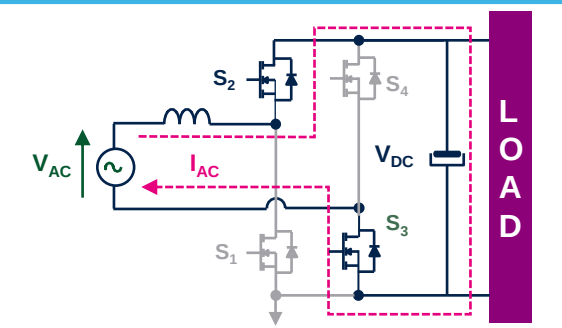
$$V_{AC} > 0$$

**S1** controls PFC choke charging  
**S3** can be switched on to reduce voltage drop of the body diode

**S1 on, inductor current rising**



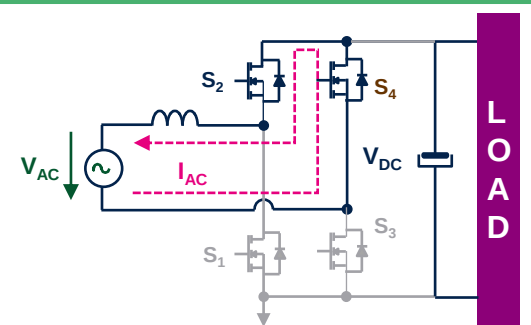
**S1 off, inductor current falling**



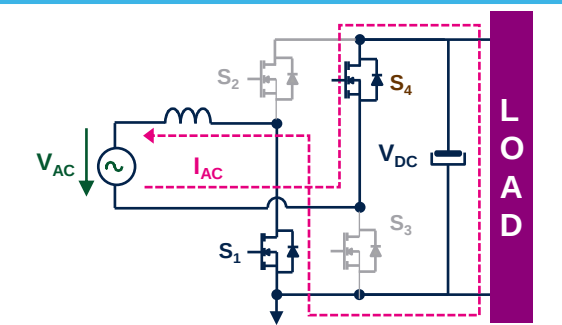
$$V_{AC} < 0$$

**S2** controls PFC choke charging  
**S4** can be switched on to reduce voltage drop of the body diode

**S2 on, inductor current rising**



**S2 off, inductor current falling**

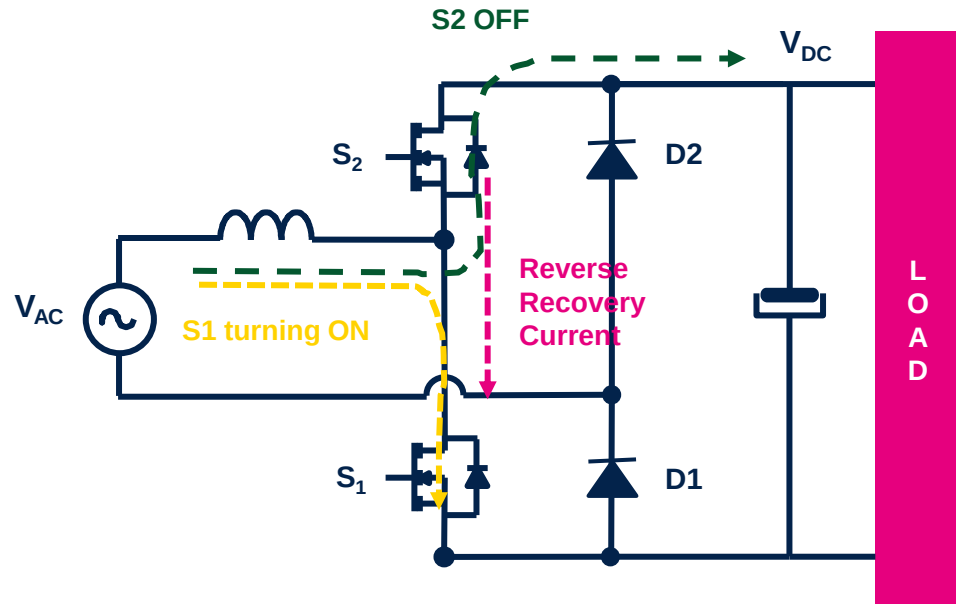




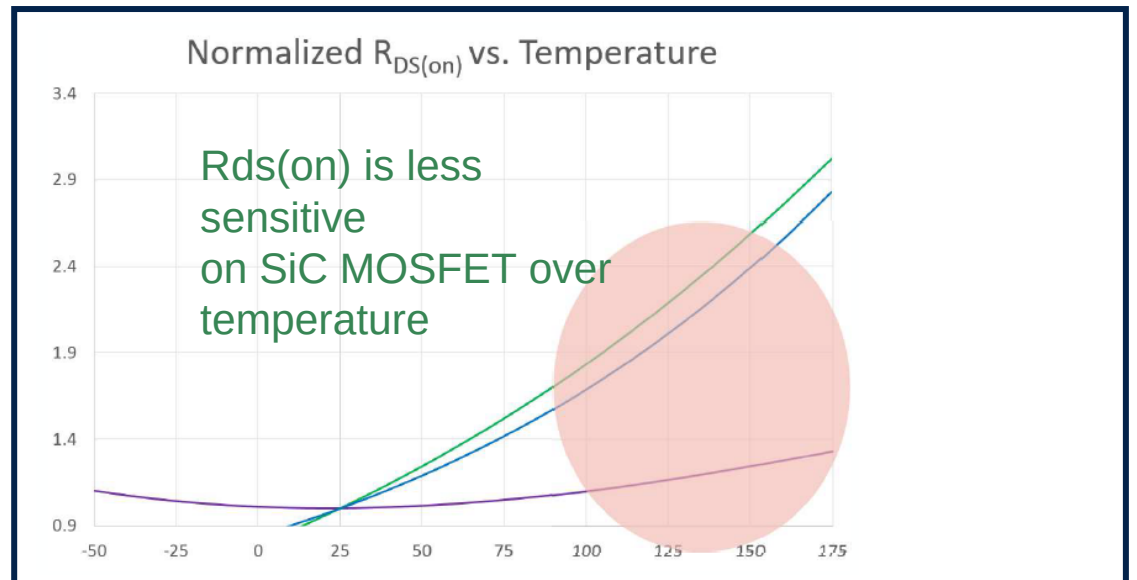
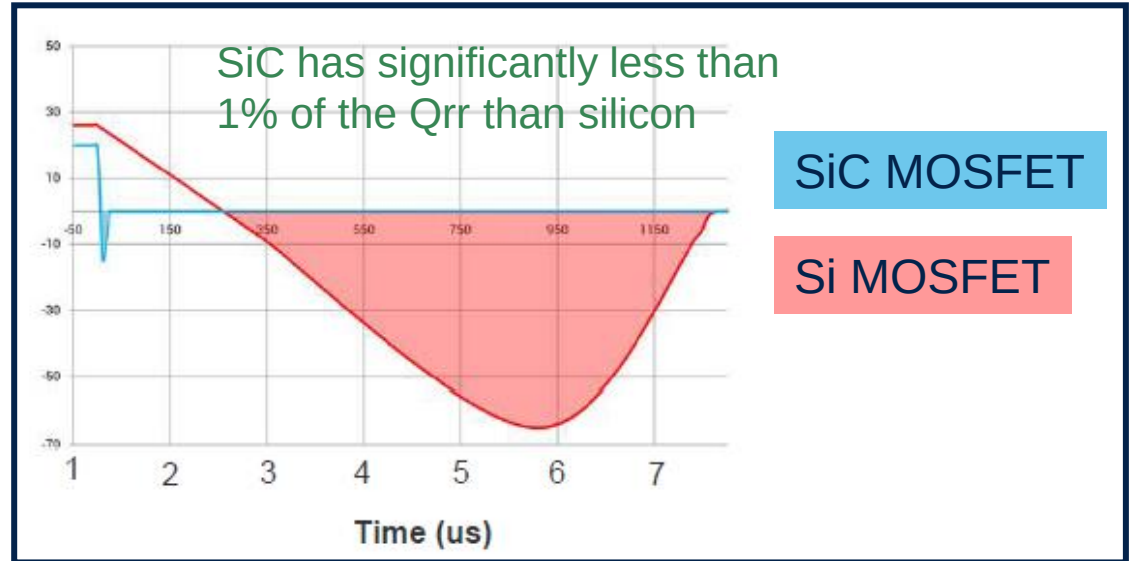


# SiC MOSFET and driver IC

## 650 V Gen2 SiC MOSFET



- Low body diode reverse recovery.
- Low switching loss due to outstanding figure of merit
- Low power loss at high temperature due to less temperature dependence of on resistance





# Resonant tank design

## Magnetizing inductance Lm selection

### Considerations:

- Select resonant frequency around 110-kHz-based power density target
- Main consideration is to achieve the optimal efficiency
- Primary MOSFET Eoff is related to Lm
- Primary MOSFET conducting loss is related to Lm
- Transformer copper loss is related to Lm
- Resonant inductor copper loss is related to Lm
- Power MOSFET ZVS is related to Lm

When operating at  $f_s=f_r=116$  kHz,  $L_m=225$   $\mu\text{H}$ :  
 RMS magnetizing current is 2.17 A  
 MOSFET switching off current is 3.752 A  
 Voltage/current phase difference is  $\Phi=0.309$   
 Total zvs discharging capability is 800 nC

## Calculation

### Check maximum Lm to ensure MOSFET ZVS at light load:

$f_{rt} := 150\text{kHz}$

*maximun switching frequency at steady status*

$C_{oss} := 286 \cdot (1 + 30\%)\text{pF} = 371.8 \cdot \text{pF}$

*output capacitor of MOSFET (considering 30% tollerance)*

$T_d := 400\text{ns}$

*deat time between MOSFETs conduction*

$C_{stray} := 100\text{pF}$

*parastic capacitor*

*the peak value of excitation current when  $L_m=L_{m\_zvs}$ , suppose the switching off current of mosfet is peak excitation current, so the current should meet ZVS condition as below:*

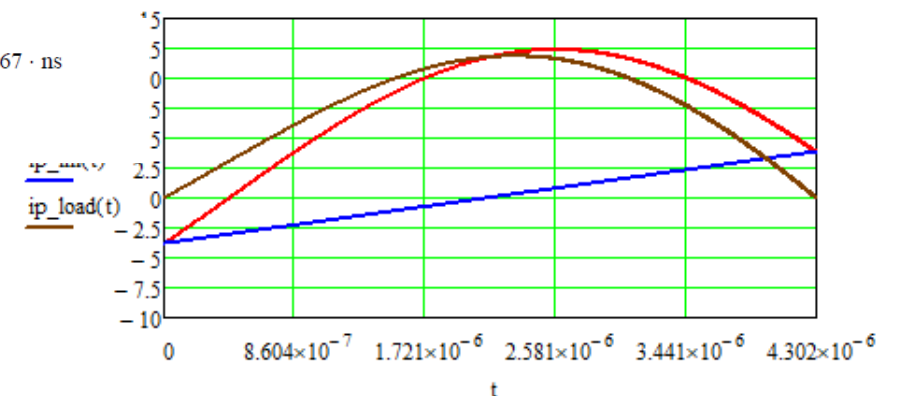
$$I(L_{m\_zvs}) := \frac{V_{pfc\_v} \cdot \left( \frac{1}{2f_{rt}} - T_d \right)}{4L_{m\_zvs}}$$

$L_{m\_zvs} := \text{root}[I(L_{m\_zvs}) \cdot T_d - (2C_{oss} + C_{stray}) \cdot V_{pfc\_t}, L_{m\_zvs}, 1\mu\text{H}, 500\mu\text{H}] = 257.892 \cdot \mu\text{H}$

### Select $L_m=230$ $\mu\text{H}$ , then double check $T_d$ margin at full load:

$$T_{d\_max} := \frac{\Phi}{\pi} \cdot \frac{1}{2f_r} = 423.467 \cdot \text{ns}$$

$T_d < T_{d\_max}$ , ok





# Resonant tank design

## Resonant tank Cr, Lr selection

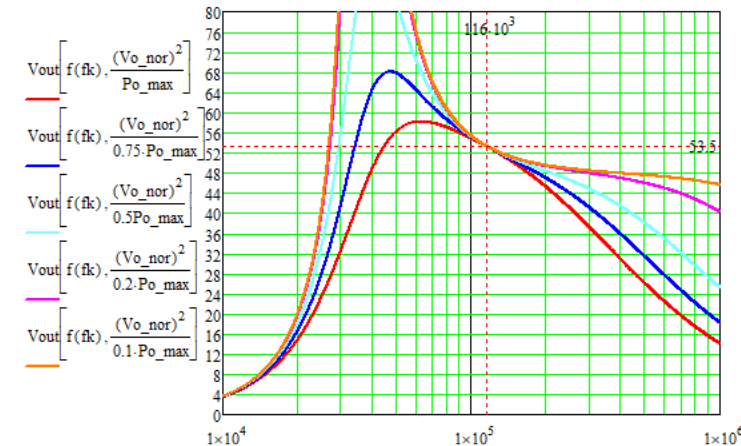
### Considerations:

- Influence for efficiency, mainly Lr
- Output voltage range and its corresponding operating frequency range
- Smaller Lr can reduce total resonant inductor power loss
- Smaller Lr will reduce output capability @ low Vin and full load
- Influence for output maintain time during shutdown
- Smaller Lr means higher frequency is needed for output regulation @ high Vin and light load

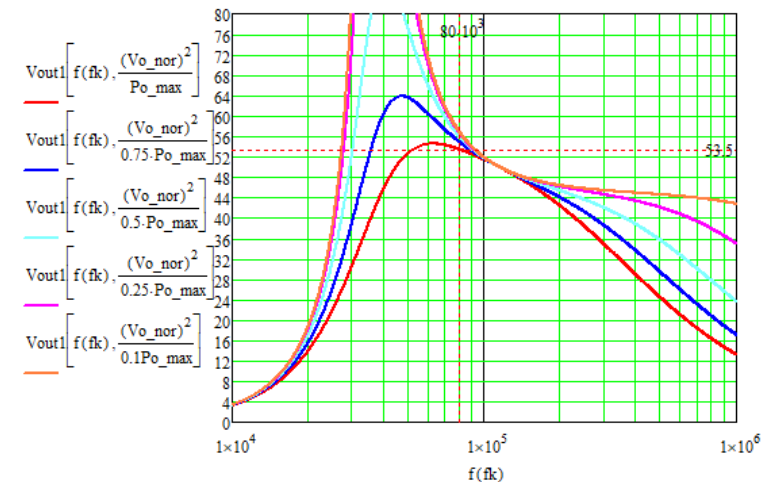
When operating with  $L_m=225 \mu\text{H}$ ,  $L_r=25 \mu\text{H}$ ,  $C_r=75 \text{ nF}$ :  
 $K=9$ ,  
 $Q=0.42$  @ full load  
 $f_s=80 \text{ kHz}$  @  $V_{in}=375 \text{ V}$ ,  $V_{out}=53.5 \text{ V}$ , full load  
 $f_s=165 \text{ kHz}$  @  $V_{in}=425 \text{ V}$ ,  $V_{out}=53.5 \text{ V}$ ,  $I_{out}=1 \text{ A}$

## Calculation

### Vout vs. fs @ Vin=400 Vdc, each load



### Vout vs. fs @ Vin=375 Vdc, each load



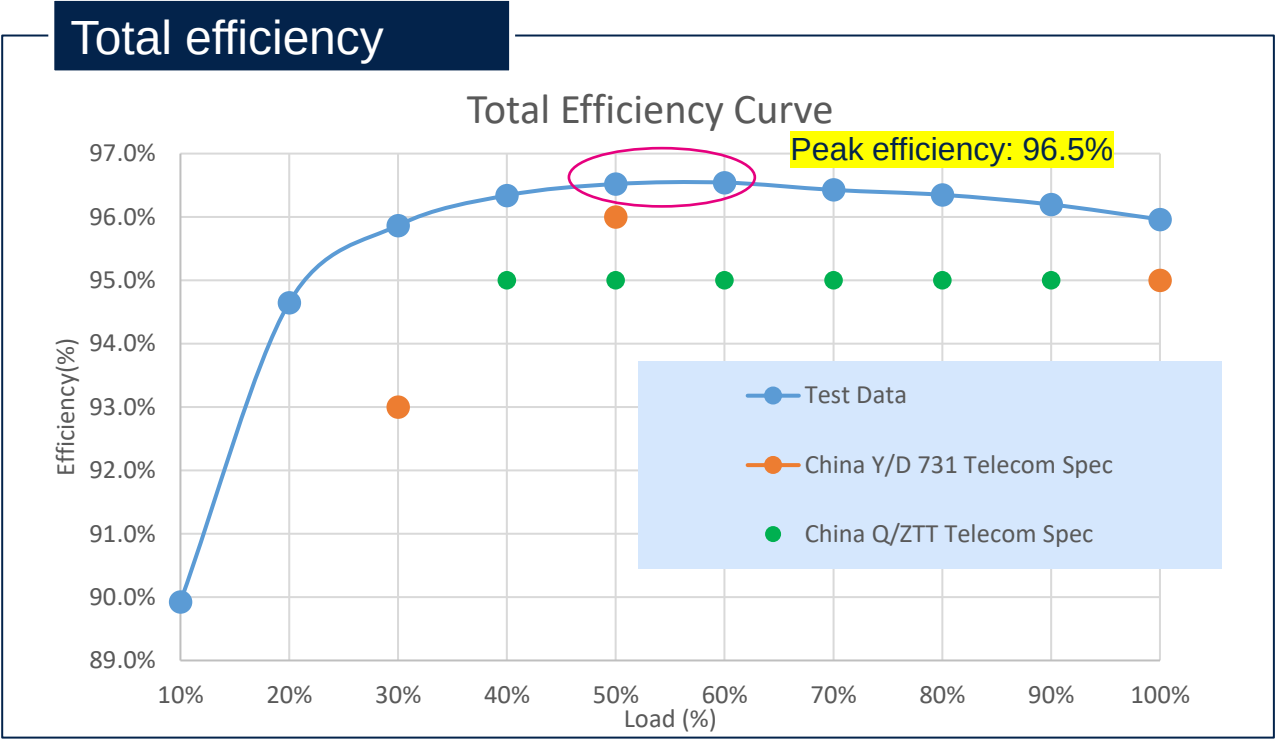
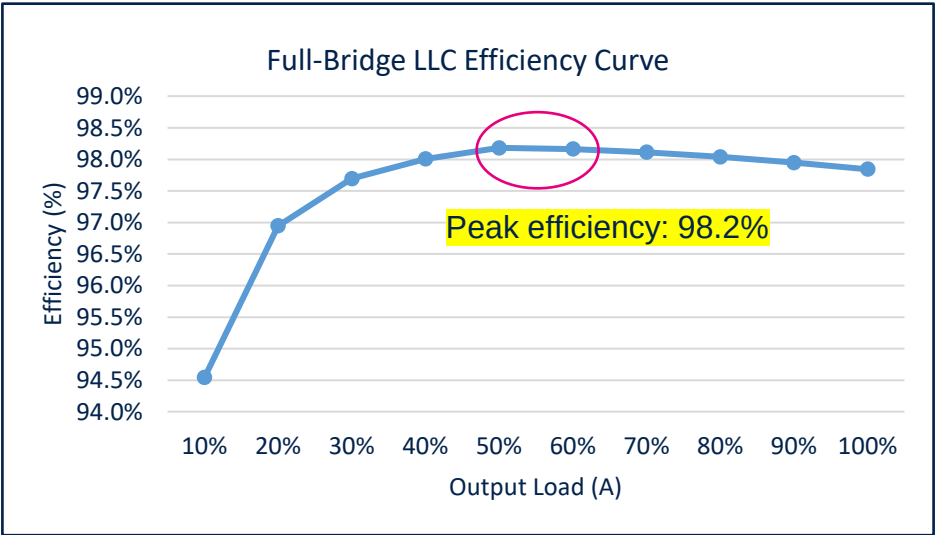
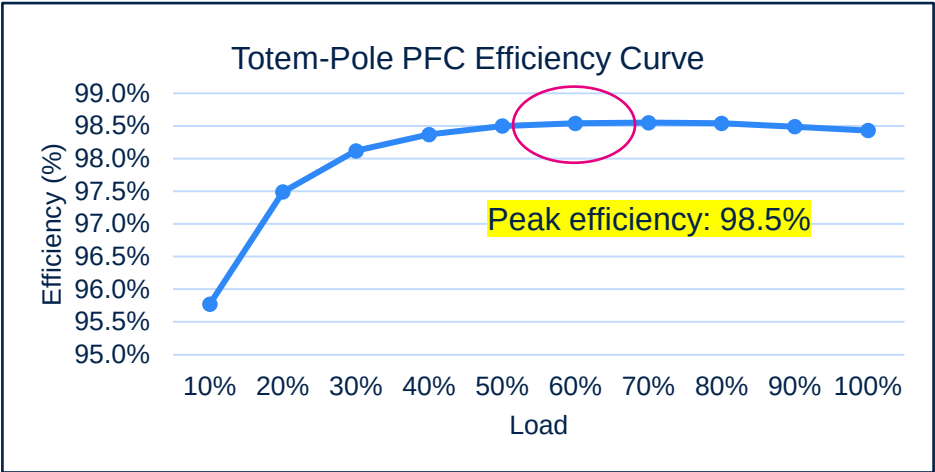
# **EVM board performance**

- Efficiency / iTHD / PF
- Soft startup
- Load transient response
- Load on with full power
- Hold-up time

Find more information from <https://www.st.com/en/evaluation-tools/stdes-3kwtlcp.html>

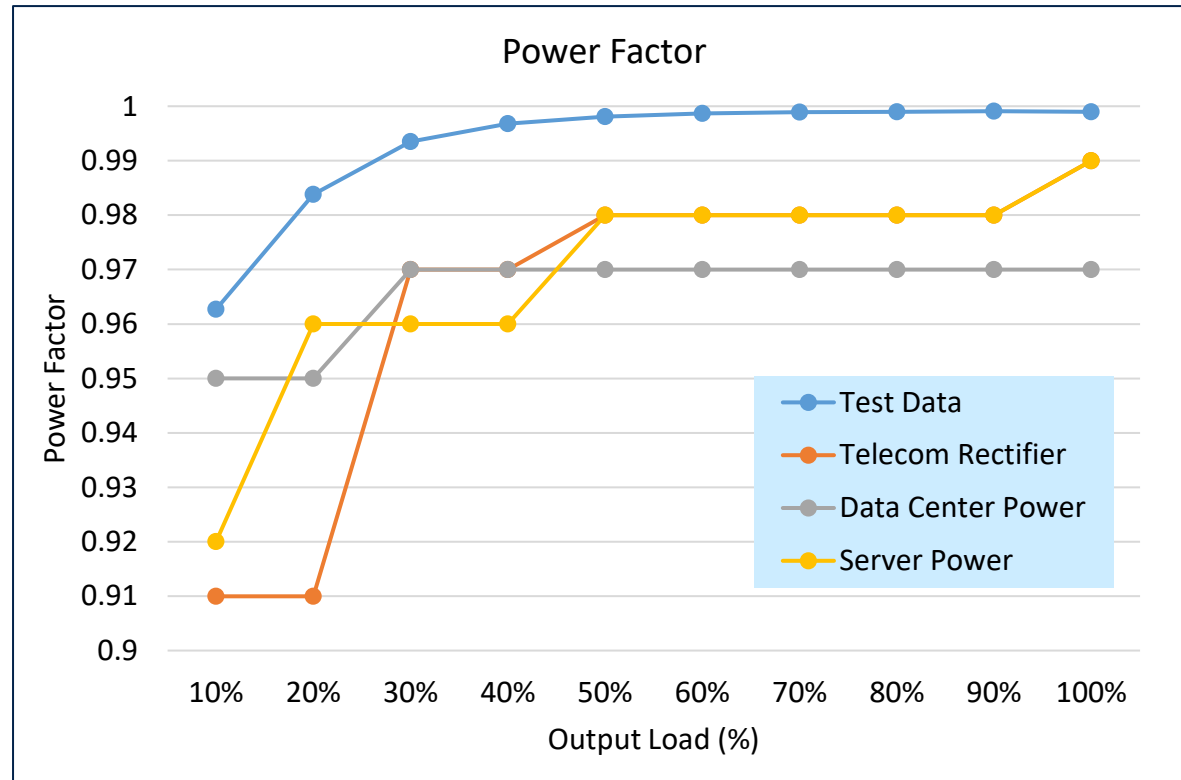


# Efficiency curve

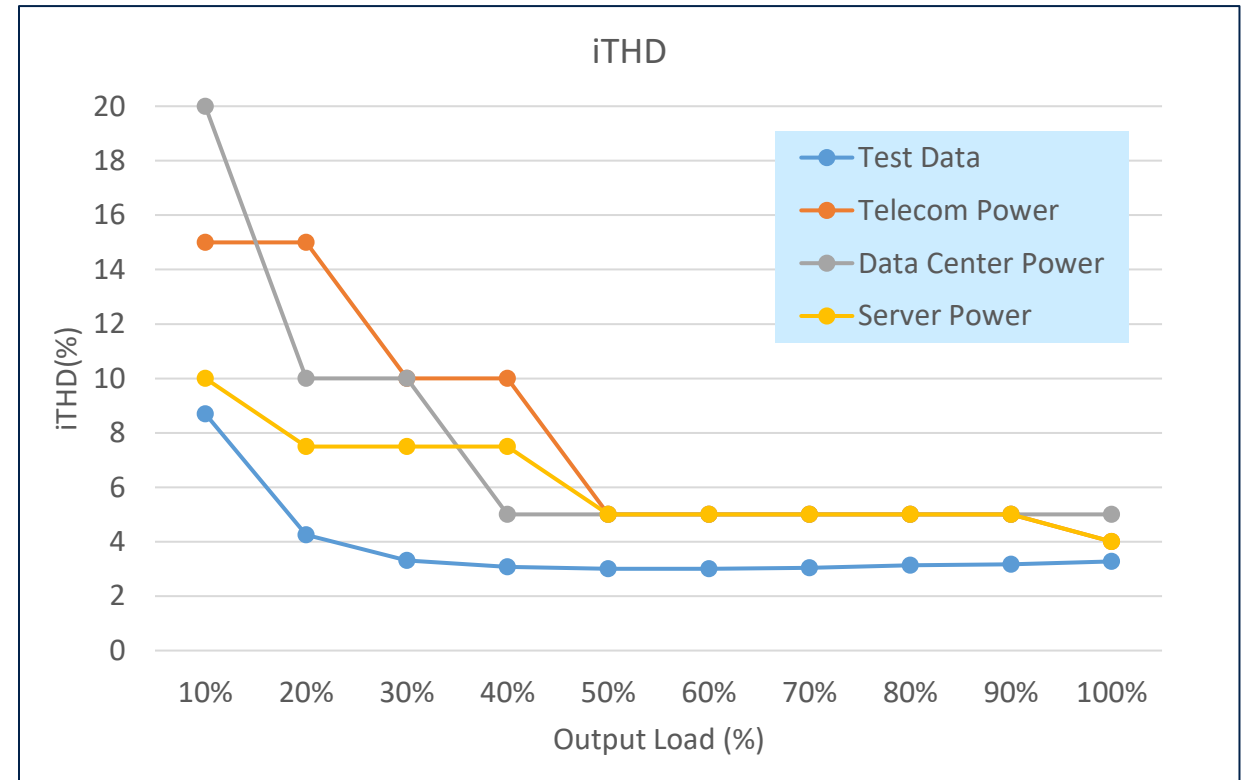


# iTHD/power factor @ 230 Vac

PF



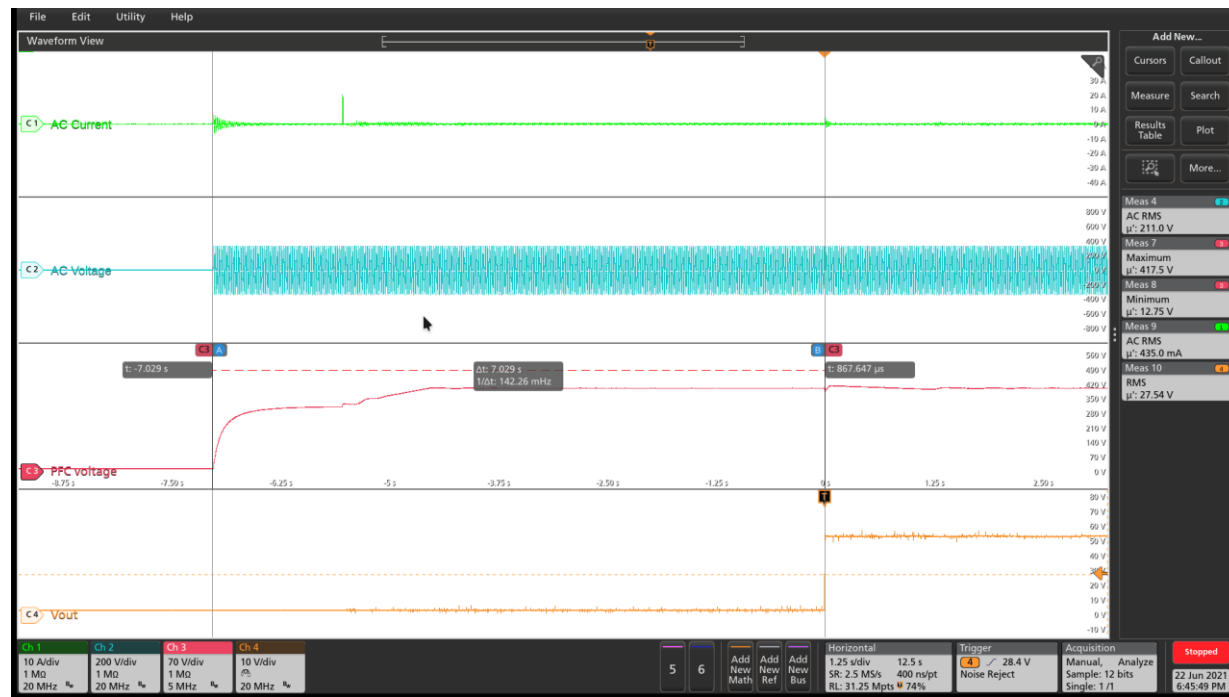
iTHD



# Soft start @ 230 Vac/50 Hz

No load

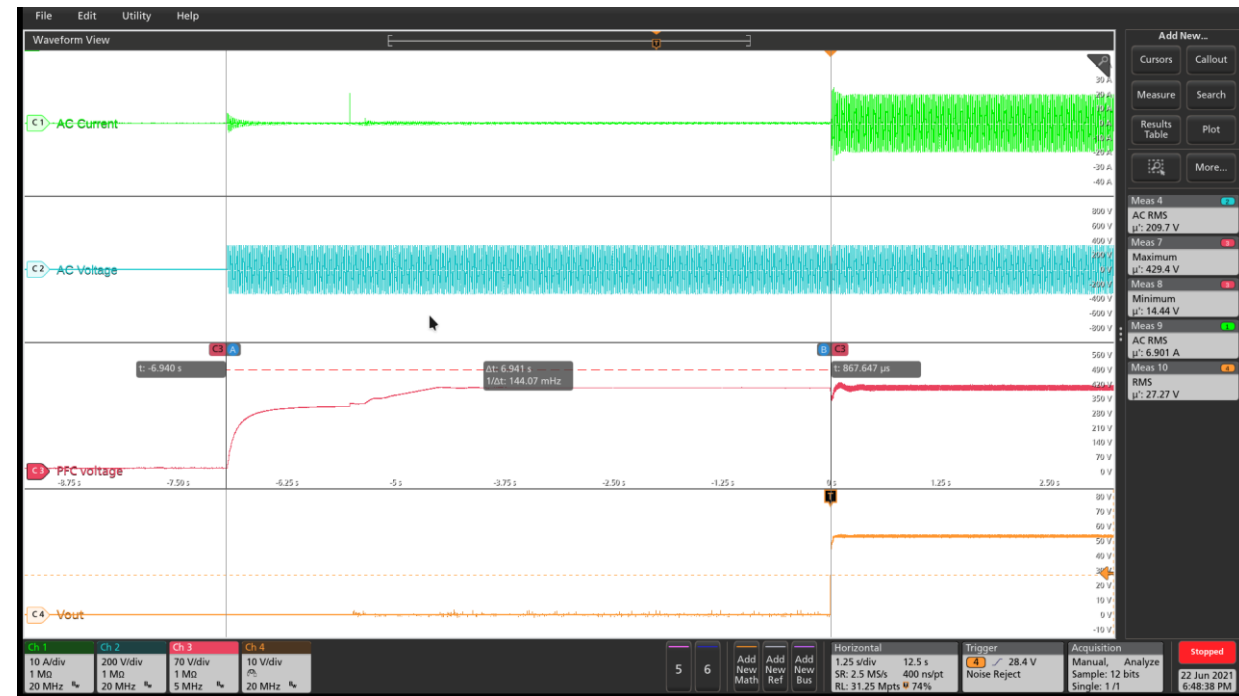
T<sub>ss</sub>=7.029 s



CH1: Input current (10 A/div)  
CH2: Input voltage (200 V/div)  
CH3: Bulk cap voltage (70 V/div)  
CH4: Output voltage (10 V/div)

Full load

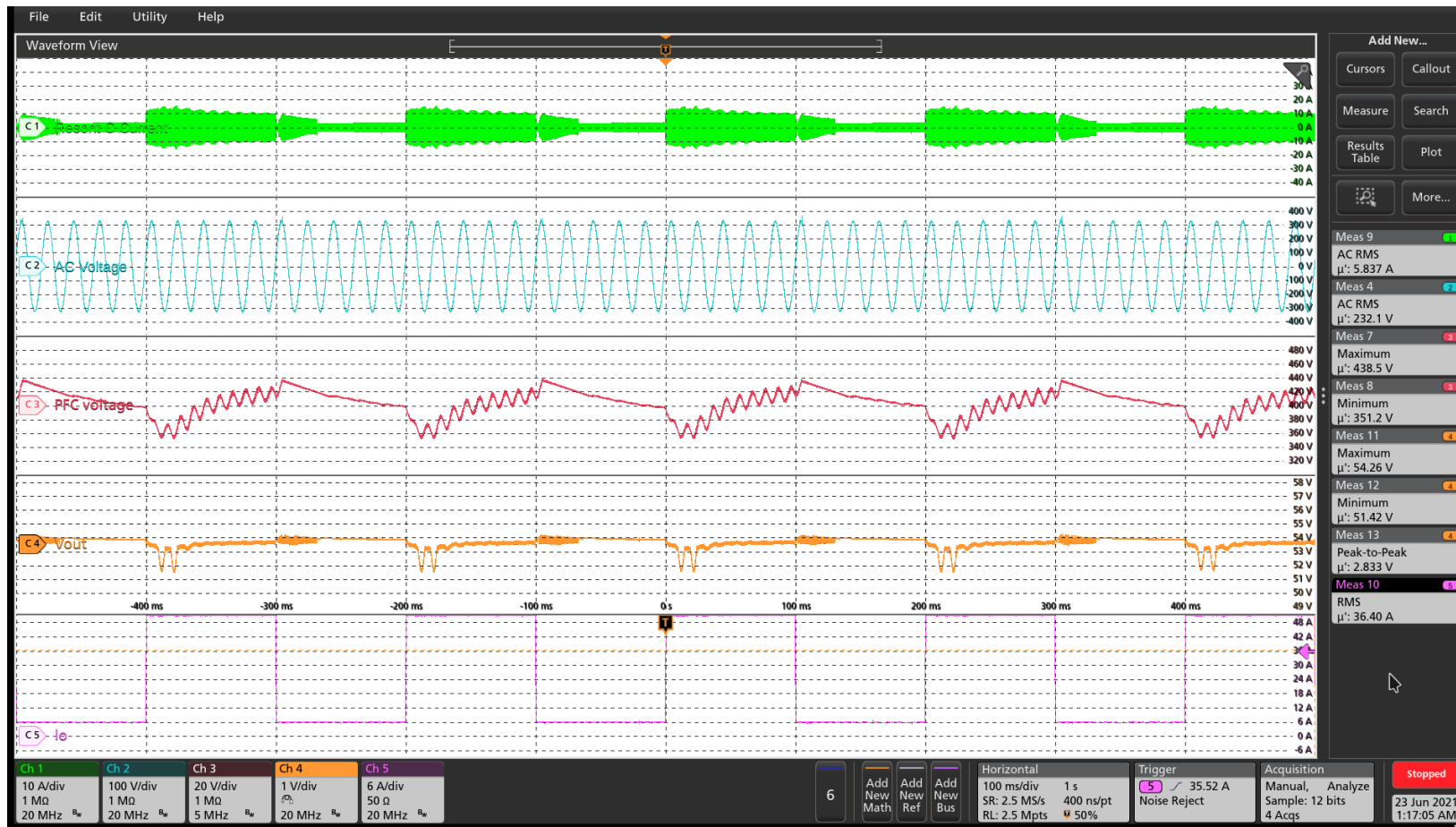
T<sub>ss</sub>=6.941 s



CH1: Input current (10 A/div)  
CH2: Input voltage (200 V/div)  
CH3: Bulk cap voltage (70 V/div)  
CH4: Output voltage (10 V/div)

# Load transient response @ 230 Vac / 50 Hz

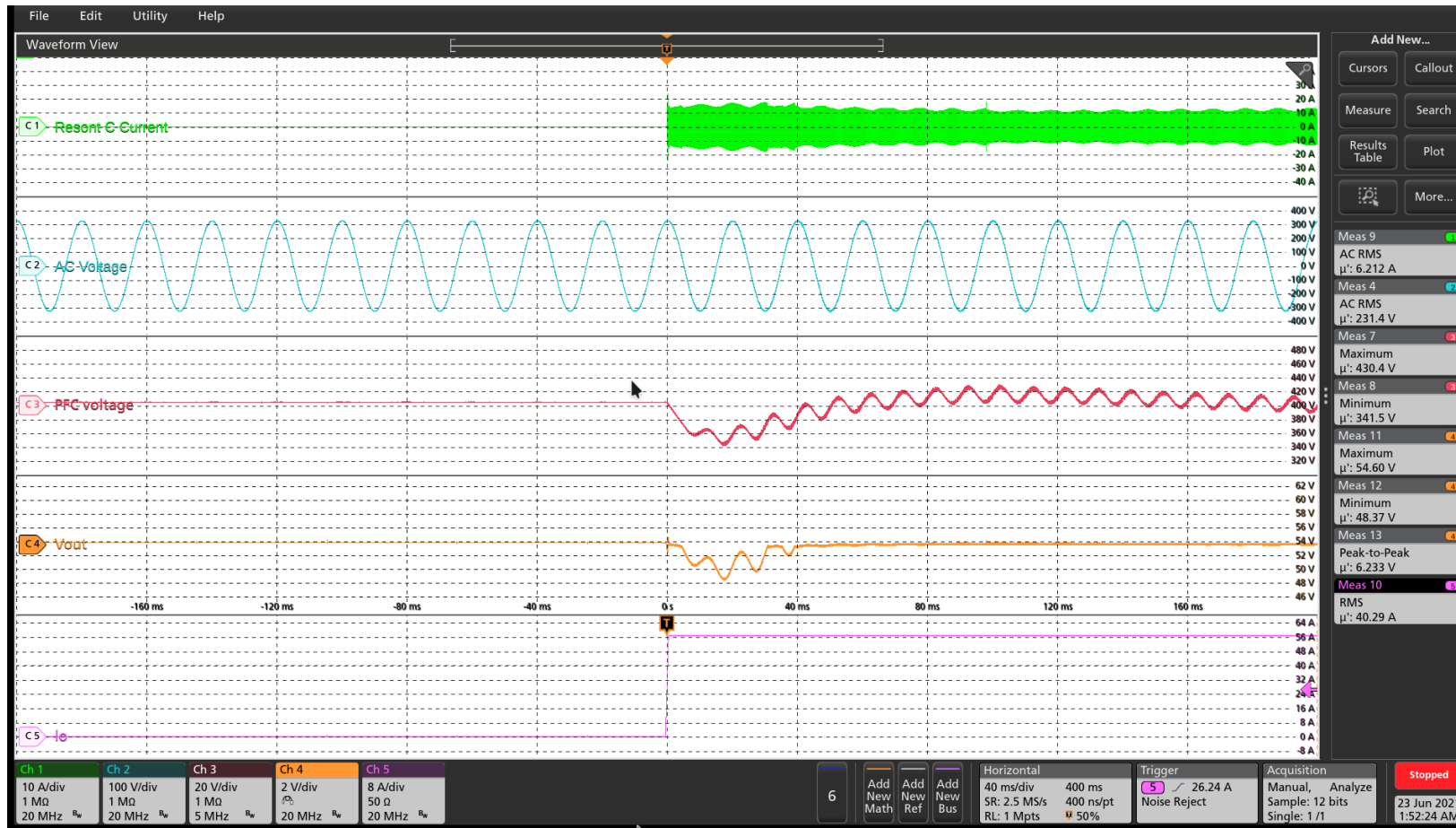
10%~90%~10% 0.1A/ $\mu$ s 100 ms



CH1: Resonant current (10 A/div)  
CH2: Input voltage (100 V/div)  
CH3: Bulk cap voltage (20 V/div  $V_{os}=400$  V)  
CH4: Output voltage (1 V/div  $V_{os}=53.5$  V)  
CH5: Load current (6 A/div)

# Load on with full power @ 230 Vac/50 Hz

Load on with full power

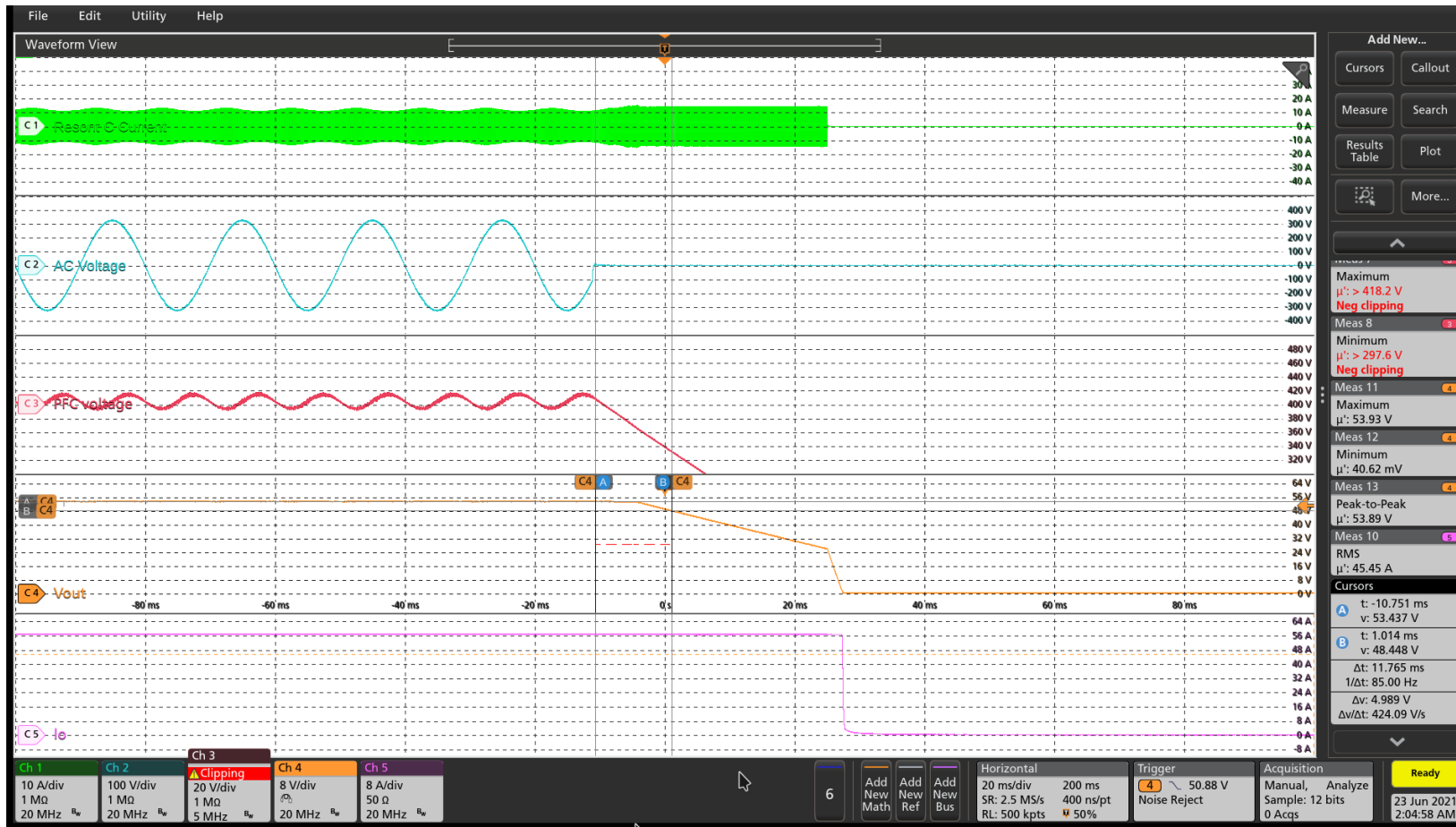


CH1: Resonant current (10 A/div)  
CH2: Input voltage (100 V/div)  
CH3: Bulk cap voltage (20 V/div Vos=400 V)  
CH4: Output voltage (2 V/div Vos=53.5 V)  
CH5: Load current (8 A/div)

# Hold up time @ 230 Vac/50 Hz

Holdup time

$T_{\text{holdup}} = 10.751 \text{ ms}$  from 53.5 V drop to 48.5 V

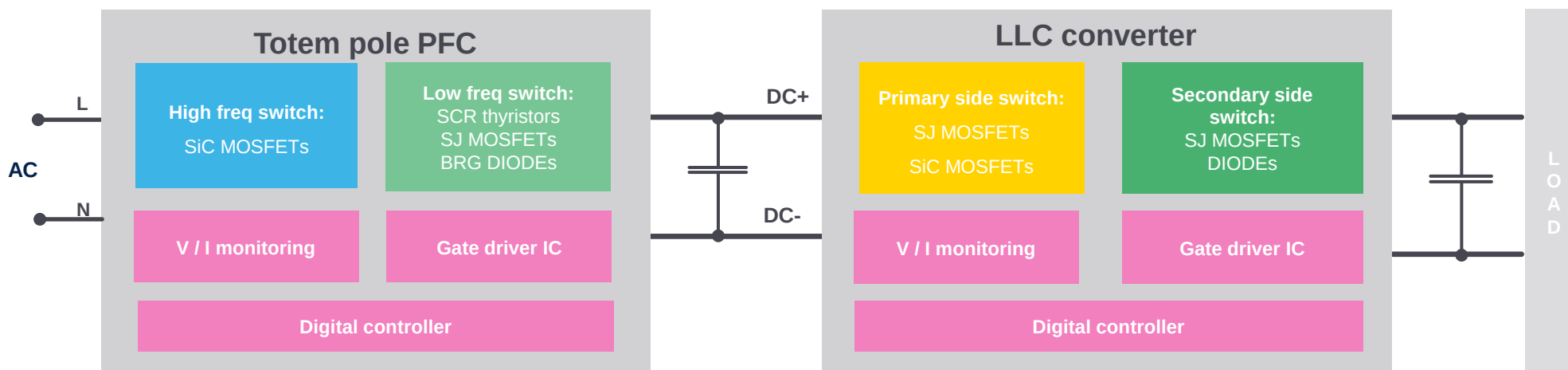
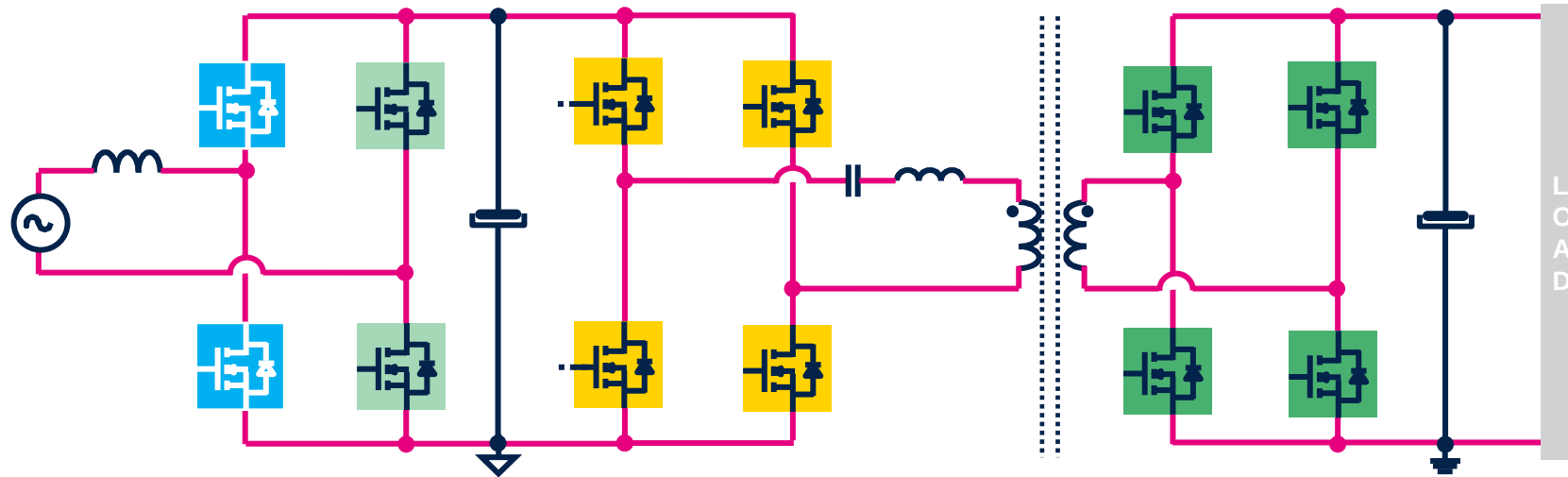


CH1: Resonant current (10 A/div)  
CH2: Input voltage (100 V/div)  
CH3: Bulk cap voltage (20 V/div  $V_{os}=400 \text{ V}$ )  
CH4: Output voltage (8 V/div)  
CH5: Load current (8 A/div)



# ST products

# ST products





# STPOWER SiC MOSFET

## Product families and applications

### Breakdown voltage

650 V

750 V/900 V

1200 V

1700 V

2200 V

### Series

G2

G3

G3

G1

G2

G3

G1

VHV

### On-state resistance

18 mΩ to  
55 mΩ

14-55 mΩ

11 mΩ

52 mΩ to  
520 mΩ

25 mΩ to  
75 mΩ

70 mΩ and  
15 mΩ

1 Ω and  
65 mΩ

31 mΩ

### Focus applications

OBC & DC-DC  
Renewable energy  
Power supply  
Industrial drives

Traction  
OBC & DC-DC  
High density  
power supply

Traction inverter  
OBC & DC-DC  
High density power  
supply

Photovoltaic  
Power supply

OBC & DC-DC  
Inverter  
Charging stations  
Industrial drives

Traction inverter  
OBC & DC-DC  
HF power supply

DC-DC  
Power  
supply  
Renewable  
energy

DC-DC  
Power  
supply  
Renewable  
energy



# High-voltage superjunction MDmesh\* series

## MDmesh series

|                            |                            |                             |                             |                              |                              |                              |                                       |
|----------------------------|----------------------------|-----------------------------|-----------------------------|------------------------------|------------------------------|------------------------------|---------------------------------------|
| <b>M2</b><br>400V to 650 V | <b>M6</b><br>600V to 650 V | <b>M5</b><br>550 V to 650 V | <b>M9</b><br>250 V to 650 V | <b>DM2</b><br>400 V to 650 V | <b>DM6</b><br>400 V to 650 V | <b>DM9</b><br>600 V to 650 V | <b>K5/DK5 - K6</b><br>800 V to 1700 V |
|----------------------------|----------------------------|-----------------------------|-----------------------------|------------------------------|------------------------------|------------------------------|---------------------------------------|

## Focus topology

|                            |                                                 |                                                                           |                                    |                  |
|----------------------------|-------------------------------------------------|---------------------------------------------------------------------------|------------------------------------|------------------|
| Flyback, PFC, LLC resonant | Hi-end-power PFC hard switching topologies, TTF | Hi-end-power PFC hard switching topologies, LLC soft switching topologies | Half Bridge, full Bridge, ZVS, LLC | Flyback topology |
|----------------------------|-------------------------------------------------|---------------------------------------------------------------------------|------------------------------------|------------------|

## Focus applications

|                                                                                 |                 |                                                           |
|---------------------------------------------------------------------------------|-----------------|-----------------------------------------------------------|
| TV SMPS, Fast chargers, adapters LED lighting, microinverters                   | EV-Car/Charging | LED driver, LED lighting, auxiliary SMPS, EV-Car, medical |
| Servers, telecom data centers, 5G power stations, solar, medical, motor control |                 |                                                           |

# Complete HV MOSFET series for higher efficiency



**Energy generation & storage** need higher & more efficient tailored topologies

**Charging station:**  
Complete solution up to 22 kW



**Server and datacenter** drive demand for better and higher power density systems

**Telecom power:** rapid increasing of smaller cells requires power system

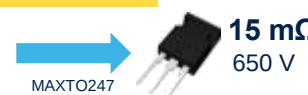


Multiple SMD and through-hole package options

## Products for applications

### PFC AC-DC converter

MDmesh **M5**



MDmesh **M9**



### DC-DC converter

MDmesh **DM2**



MDmesh **DM6**



MDmesh **DM9**



### Flyback section

MDmesh **K5**



MDmesh **K6**



# Isolated gate drive for SiC MOSFET

1700 V galvanic isolated single & dual channel



SO-8

STGAP2S  
STGAP2SC  
STGAP2SICSN  
STGAP2SICSNC



SO-16

STGAP2D

Galvanic isolated, up to  
1700 V high voltage rail

Extreme transient  
immunity up to  
 $\pm 100 \text{ V / ns}$



Fast switching frequency  
(Tp 80 ns only)

High current capability  
4A Isink / Isource

6000 V galvanic isolated single & dual channel



SO-8W

STGAP2HS  
STGAP2HSC  
STGAP2SICS  
STGAP2SICSC



SO-36W

STGAP2HD  
STGAP2SICD

Galvanic isolated, up to  
6000 V high voltage rail

Extreme transient  
immunity up to  
 $\pm 100 \text{ V / ns}$

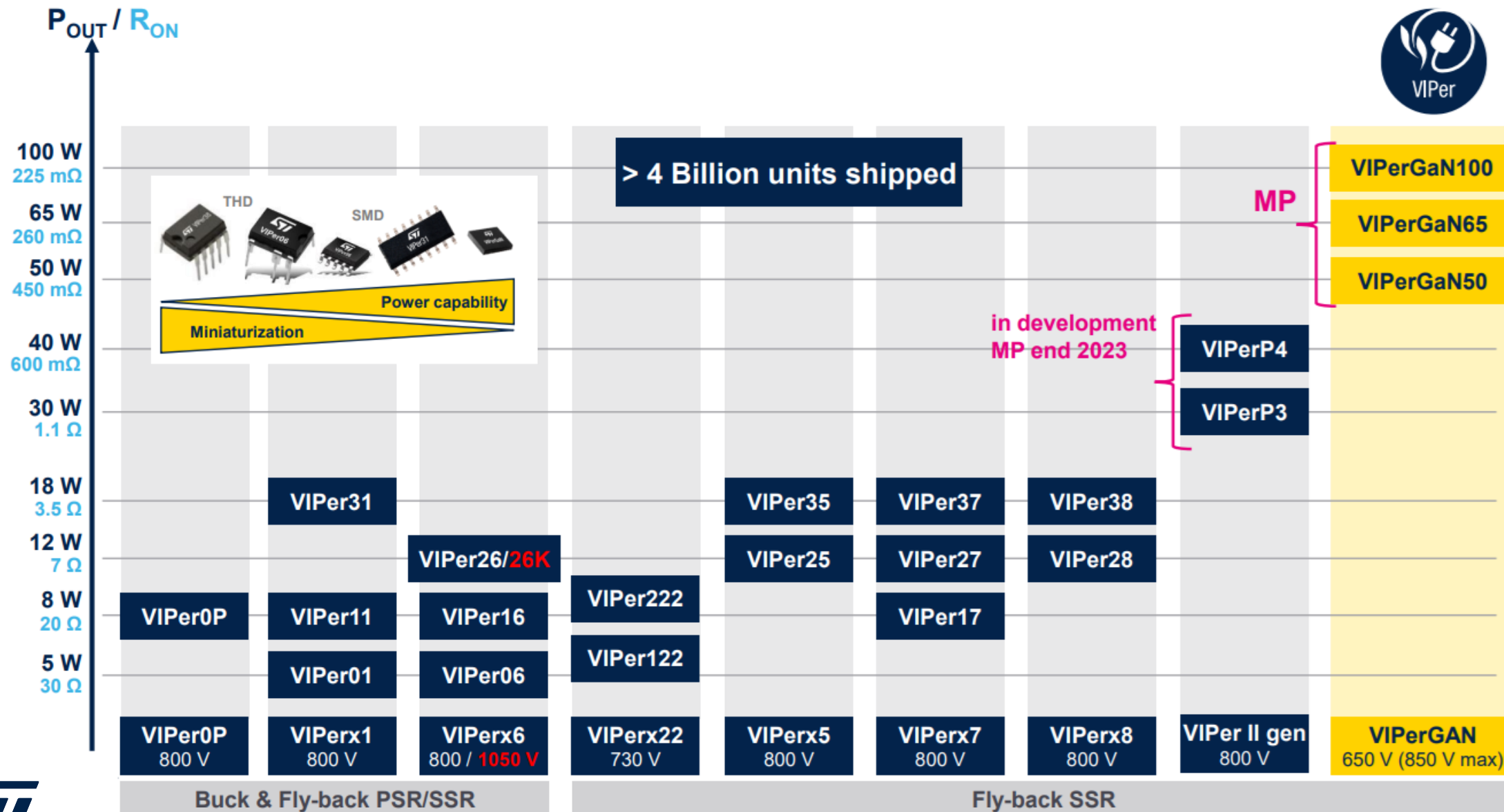


Fast switching frequency  
(Tp 80 ns only)

High current capability  
4A Isink / Isource



# VIPer family



# STM32G474 MCU

**Based on a 32-bit Arm® Cortex® -M4 core with FPU and DSP instructions running at 170 MHz, ideal for digital power conversion**

- 170 MHz 32-bit Arm Cortex®-M4 core with FPU
- Routine booster of CCM-SRAM up to 32 KB
- Mathematic hardware accelerators (CORDIC / FMAC)
- High-resolution timer (184 ps) for precise PWM control
- Rich advanced analog
- USB Type-C® Power Delivery (PD)
- $\pm 1\%$  internal clock

## MAIN APPLICATIONS



Commercial, architectural and street lighting



Server/Telecom



Welding



Charging station



UPS & Data center Power supply



Solar inverters



life.augmented



## Connectivity

4x SPI, 4x I<sup>2</sup>C, 6x UxART

1x USB 2.0 FS,  
1x USB-C PD3.0 (+PHY)

3x CAN-FD

2x I<sup>2</sup>S half duplex, SAI

## External interface

FSMC 8-/16-bit (TFT-LCD, SRAM, NOR, NAND)

Quad SPI

## Accelerators

ART Accelerator™

32-Kbyte CCM-SRAM

## Math Accelerators

Cordic (trigo...)  
Filtering

Arm® Cortex®-M4  
Up to 170 MHz  
213 DMIPS

Floating Point Unit

Memory Protection Unit

Embedded Trace  
Macrocell

16-channel DMA + MUX

Up to 2x 256-Kbyte  
Flash memory / ECC  
Dual Bank

96-Kbyte SRAM

## Timers

5x 16-bit timers

2x 16-bit basic timers

3x 16-bit advanced  
motor control timers

2x 32-bit timers

1x 16-bit LP timer

1x HR timer (D-Power)  
12-channel w/ 184ps  
(A. delay line)

## Analog

5x 12-bit ADC w/ HW overspl

7x Comparators

7x DAC (3x buff + 4x non-buff)

6x Op-Amp (PGA)

1x temperature sensor

Internal voltage reference

# Summary



# Summary

- This digital solution with **STM32G4** will help you achieve **high efficiency / high power density** for 5G telecom power supply
- ST provides the latest technologies (SiC/STGAP/M6/STM32) for high power density and high efficiency solutions on 5G telecom power applications.
- This reference design offers:
  - Digital power solution for totem pole PFC converter and full-bridge LLC with synchronous rectifiers
  - Peak efficiency is greater than 96.5%, PFC section is 98.5%, DC-DC section is 98.2%
  - Power density up to 40 W/in<sup>3</sup>
  - iTHD distortion lower than 5% and PF greater than 0.99
  - Adaptive SR control algorithm for efficiency optimization

# Our technology starts with You



Find out more at [www.st.com](http://www.st.com)

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